

Chinese and English Definitions of Acronyms Related to Ethernet Products

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ABSTRACT

The Chinese and English Definitions of Acronyms Related to Ethernet Products application report is intended to provide standardized definitions for commonly used acronyms in both Chinese and English.

Contents

| | | |
|---|-------------------------------|---|
| 1 | Introduction | 1 |
| 2 | Acronyms and Definitions..... | 1 |

1 Introduction

This application report is intended to provide a standardized acronym reference for both Chinese and English users. [Table 1](#) is sorted alphabetically for ease of search and reference.

2 Acronyms and Definitions

Table 1. Acronyms Definitions

| Acronym (缩写) | English Definition (英文注释) | Chinese Definition (中文注释) |
|--------------|--------------------------------------------------------|---------------------------|
| ADC | Analog to Digital Converter | 模拟/数字转换器 |
| AEQ | Adaptive Equalizer | 自适应均衡器 |
| ALCD | Active Link Cable Diagnostics | 动态链路电缆诊断 |
| AVB | Audio Video Bridging | 音频视频桥接 |
| AVD | Analog Voltage Supply | 模拟电源 |
| BMC | Best Master Clock | 最佳主时钟算法 |
| CAT5 | Category-5 Cable | 第五类双绞线 |
| CDM | Charged-Device Model | 充电器件模型 |
| CMC | Common Mode Choke | 共模电感线圈 |
| CML | Current Mode Line Driver | 电流驱动器 |
| COL | Collision Detect | 冲突监测 |
| CRC | Cyclic Redundancy Check | 循环冗余检查 |
| CRS | Carrier Sense | 载波侦听 |
| CRS_DV | Carrier Sense / Receive Data Valid | 载波侦听 / 接收数据有效信号 |
| CSMA/CD | Carrier Sense Multiple Access with Collision Detection | 载波监听多路访问技术 |
| CT | Center Tap Supply Rail | 中点抽头电源 |
| DAC | Digital to Analog Converter | 数字/模拟转换器 |
| DDR | Double Data Rate | 双倍数据速率 |
| DEST | Destination Address | 终点地址 |
| DEVAD | Device Address | 装置地址 |
| DUT | Device Under Test | 被测试元件 |

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Table 1. Acronyms Definitions (continued)

| Acronym (缩写) | English Definition (英文注释) | Chinese Definition (中文注释) |
|--------------|---------------------------------------------------|---------------------------|
| EEE | Energy Efficient Ethernet | 节能以太网 |
| EMC | Electromagnetic Compatibility | 电磁兼容 |
| EMI | Electromagnetic Interference | 电磁干扰 |
| EMS | Electromagnetic Susceptibility | 电磁屏蔽 |
| ESD | Electrostatic Discharge | 静电放电 |
| EVM | Evaluation Module | 评估模块 |
| FLP | Fast Link Pulse | 快速链路脉冲 |
| FX | Fiber | 光纤 |
| GMII | Gigabit Media Independent Interface | 千兆媒体独立接口 |
| GND | Ground | 接地端 |
| GPIO | General Purpose Input/Output | 通用输入输出口 |
| HBM | Human Body Model | 人体模型 |
| ID | Internal Delay | 内部延迟 |
| IEC | International Electrotechnical Commission | 国际电工委员会 |
| IEEE | Institute of Electrical and Electronics Engineers | 电气和电子工程师协会 |
| IPG | Inter-Packet Gap | 数据包间隔 |
| JTAG | Joint Test Action Group | 联合测试工作组 |
| LP | Link Partner | 链接对象 |
| LPI | Low-Power Idle | 低功耗闲置 |
| MAC | Media Access Controller | 介质访问控制器 |
| MDC | Management Data Clock | 管理数据时钟 |
| MDI | Media Dependent Interface | 介质有关接口 |
| MDIO | Management Data I/O | 管理数据输入输出口 |
| MDIX | Media Dependent Interface Crossover | 介质有关交叉接口 |
| MII | Media Independent Interface | 媒介独立接口 |
| MLT-3 | 3 level Multi Level Transitions | 多电平传输-3 |
| MM | Machine Model | 机器模型 |
| NLP | Normal Link Pulse | 正常链路脉冲 |
| Opcode | Operation Code | 操作代码 |
| PAM | Pulse Amplitude Modulation | 脉冲振幅调变 |
| PCS | Physical Coding Sublayer | 物理编码子层 |
| PD | Pull-Down | 下拉 |
| PHY | Physical Layer | 物理层 |
| PHYAD | Physical Layer Address | 物理层地址 |
| PLL | Phase Lock Loop | 锁相环 |
| PMA | Physical Medium Attachment Sublayer | 物理媒介连接子层 |
| PMD | Physical Medium Dependent Sublayer | 物理介质相关子层 |
| PoE | Power over Ethernet | 以太网供电 |
| PTP | Precision Time Protocol | 精确时钟同步协议 |
| PU | Pull-Up | 上拉 |
| QFN | Quad Flat No-leads package | 方形扁平无引脚封装 |
| QFP | Quad Flat Package | 方形扁平式封装 |
| RBIAS | Bias Resistor | 偏置电阻器连接 |
| RD | Differential Receive Input | 差分信号输入 |
| RGMII | Reduced Gigabit Media Independent Interface | 简化千兆媒介独立接口 |
| RMII | Reduced Media Independent Interface | 简化媒介独立接口 |
| RX | Receive | 接收 |

Table 1. Acronyms Definitions (continued)

| Acronym (缩写) | English Definition (英文注释) | Chinese Definition (中文注释) |
|--------------|-------------------------------------------------|---------------------------|
| RX_CLK | Receive Clock | 接收时钟信号 |
| RX_CTRL | Receive Control | 接收启动和数据错误信号 |
| RX_D | Receive Data | 接收数据 |
| RX_DV | Receive Data Valid | 接收数据有效信号 |
| RX_ER | Receive Error | 接收数据错误信号 |
| SFD | Start Frame Delimiter | 起始帧分界符 |
| SFF | Small Form Factor | 小封装技术 |
| SFP | Small Form-Factor Pluggable (Fiber Transceiver) | 小封装可插拔收发器 |
| SGMII | Serial Gigabit Media Independent Interface | 串行千兆媒介独立接口 |
| SMI | Serial Management Interface | 串行管理接口 |
| SNI | Serial Network Interface | 串行网络接口 |
| SOC | System on Chip | 系统级芯片 |
| SRC | Source Address | 源头地址 |
| STP | Shielded Twisted Pair | 屏蔽双绞线 |
| TD | Differential Transmit Output | 发送差分信号 |
| TDR | Time Domain Reflectometry | 时域反射技术 |
| TSN | Time Sensitive Networking | 时效性网络 |
| TX | Transmit | 发送 |
| TX_CLK | Transmit Clock | 发送时钟信号 |
| TX_CTRL | Transmit Control | 发送启动和数据错误信号 |
| TX_D | Transmit Data | 发送数据 |
| TX_EN | Transmit Enable | 发送启用信号 |
| TX_ER | Transmit Error | 发送数据错误信号 |
| UTP | Unshielded Twisted Pair | 非屏蔽双绞线 |
| VDDIO | I/O Voltage Supply | 输入输出电源 |
| VML | voltage mode line driver | 电压驱动器 |
| WoL | Wake-on-LAN | 远程唤醒技术 |
| WQFN | Thin Quad Flat No-lead | 极细方形扁平无引脚封装 |
| XI | Crystal/Oscillator Input | 晶振/振荡器输入 |
| XO | Crystal output | 晶振输出 |

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